

FEATURES

- High saturated output power (P_{SAT}): 25 dBm
- High output third-order intercept (IP3): 35 dBm
- High gain: 22 dB (24 GHz to 27 GHz)
- High output power for 1 dB compression (P_{1dB}): 24 dBm
- DC supply: 5 V at 225 mA
- Compact 24-lead, 4 mm × 4 mm LCC package

APPLICATIONS

- Point-to-point radios
- Point-to-multipoint radios
- VSAT and SATCOM

FUNCTIONAL BLOCK DIAGRAM

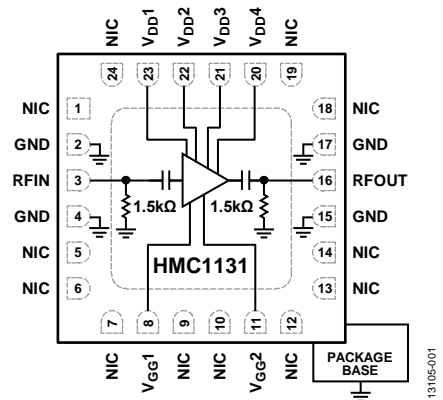


Figure 1.

GENERAL DESCRIPTION

The **HMC1131** is a gallium arsenide (GaAs), pseudomorphic high electron mobility transfer (pHEMT), monolithic microwave integrated circuit (MMIC), driver amplifier that operates from 24 GHz to 35 GHz. The **HMC1131** provides 22 dB of gain at the 24 GHz to 27 GHz range, 35 dBm output IP3, and 24 dBm of output power at 1 dB gain compression, while requiring 225 mA

from a 5 V supply. The **HMC1131** is capable of supplying 25 dBm of saturated output power and is housed in a compact, 4 mm × 4 mm ceramic leadless chip carrier (24-lead LCC). The **HMC1131** is an ideal driver amplifier for a wide range of applications, including point-to-point radios, from 24 GHz to 35 GHz.

HMC1131* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS

View a parametric search of comparable parts.

EVALUATION KITS

- HMC1131 Evaluation Board

DOCUMENTATION

Application Notes

- AN-1363: Meeting Biasing Requirements of Externally Biased RF/Microwave Amplifiers with Active Bias Controllers
- Broadband Biasing of Amplifiers General Application Note
- MMIC Amplifier Biasing Procedure Application Note
- Thermal Management for Surface Mount Components General Application Note

Data Sheet

- HMC1131: GaAs, pHEMT, MMIC, Medium Power Amplifier, 24 GHz to 35 GHz Data Sheet

TOOLS AND SIMULATIONS

- HMC1131LC4 S-Parameters

REFERENCE MATERIALS

Press

- Medium-Power Driver Amplifier Delivers High Gain and Output Power for Easy Integration in Communications Systems

DESIGN RESOURCES

- HMC1131 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all HMC1131 EngineerZone Discussions.

SAMPLE AND BUY

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK

Submit feedback for this data sheet.

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REVISION HISTORY

9/15—Rev. 0 to Rev. A

| | |
|--|---|
| Changes to Features Section and General Description..... | 1 |
| Change to Gain Parameter, Table 1 | 3 |

7/15—Revision 0: Initial Version

ELECTRICAL SPECIFICATIONS

24 GHz TO 27 GHz FREQUENCY RANGE

$T_A = 25^\circ\text{C}$, $V_{DD1} = V_{DD2} = V_{DD3} = V_{DD4} = 5\text{ V}$, $I_{DD} = 225\text{ mA}$, unless otherwise stated. Adjust V_{GG1} and V_{GG2} between -2 V to 0 V to achieve $I_{DD} = 225\text{ mA}$ typical.

Table 1.

| Parameter | Symbol | Min | Typ | Max | Unit |
|---|-----------|-----|-------|-----|-------|
| FREQUENCY RANGE | | 24 | | 27 | GHz |
| GAIN | | 18 | 22 | | dB |
| Gain Variation Over Temperature | | | 0.031 | | dB/°C |
| RETURN LOSS | | | | | |
| Input | | | 8 | | dB |
| Output | | | 7 | | dB |
| OUTPUT | | | | | |
| Output Power for 1 dB Compression | P1dB | 20 | 23 | | dBm |
| Saturated Output Power | P_{SAT} | | 27 | | dBm |
| Output Third-Order Intercept ¹ | IP3 | | 34 | | dBm |
| SUPPLY CURRENT | | | | | |
| Total Supply Current | I_{DD} | | 225 | | mA |
| Total Supply Current vs. V_{DD}^2 | | | 4 | | V |
| | | | 5 | | V |

¹ Measurement taken at $P_{OUT}/\text{tone} = 10\text{ dBm}$.

² The amplifier operates over the full voltage ranges shown. V_{GG1} and V_{GG2} are adjusted to achieve $I_{DD} = 225\text{ mA}$ at 5 V .

27 GHz TO 35 GHz FREQUENCY RANGE

$T_A = 25^\circ\text{C}$, $V_{DD1} = V_{DD2} = V_{DD3} = V_{DD4} = 5\text{ V}$, $I_{DD} = 225\text{ mA}$, unless otherwise stated. Adjust V_{GG1} and V_{GG2} between -2 V to 0 V to achieve $I_{DD} = 225\text{ mA}$ typical.

Table 2.

| Parameter | Symbol | Min | Typ | Max | Unit |
|---|-----------|-----|-------|-----|-------|
| FREQUENCY RANGE | | 27 | | 35 | GHz |
| GAIN | | 18 | 20 | | dB |
| Gain Variation Over Temperature | | | 0.031 | | dB/°C |
| RETURN LOSS | | | | | |
| Input | | | 8 | | dB |
| Output | | | 7 | | dB |
| OUTPUT | | | | | |
| Output Power for 1 dB Compression | P1dB | 21 | 24 | | dBm |
| Saturated Output Power | P_{SAT} | | 25 | | dBm |
| Output Third-Order Intercept ¹ | IP3 | | 35 | | dBm |
| SUPPLY CURRENT | | | | | |
| Total Supply Current | I_{DD} | | 225 | | mA |
| Total Supply Current vs. V_{DD}^2 | | | 4 | | V |
| | | | 5 | | V |

¹ Measurement taken at $P_{OUT}/\text{tone} = 10\text{ dBm}$.

² The amplifier operates over the full voltage ranges shown. V_{GG1} and V_{GG2} are adjusted to achieve $I_{DD} = 225\text{ mA}$ at 5 V .

ABSOLUTE MAXIMUM RATINGS

Table 3.

| Parameter | Rating |
|--|--------------------------|
| Drain Bias Voltage (V_{DD}) | 5.5 V |
| RF Input Power (RFIN) | 12 dBm |
| Channel Temperature | 175°C |
| Continuous Power Dissipation (P_{DISS}), $T_A = 85^\circ\text{C}$ (Derate 22 mW/°C) | 1.97 W |
| Thermal Resistance, R_{TH} (Junction to Ground Paddle) | 45.5°C/W |
| Operating Temperature | -40°C to +85°C |
| Storage Temperature | -65°C to +150°C |
| ESD Sensitivity, Human Body Model (HBM) | Class 0, passed 150 V |
| Maximum Peak Reflow Temperature | 260°C |

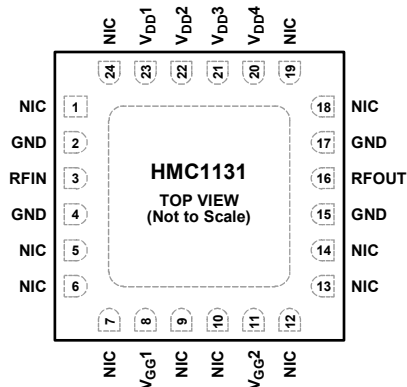
Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



NOTES
 1. NIC = NOT INTERNALLY CONNECTED.
 2. THE EXPOSED PAD MUST BE CONNECTED TO RF/DC GROUND.

13105-100

Figure 2. Pin Configuration

Table 4. Pin Function Descriptions

| Pin No. | Mnemonic | Description |
|--|--------------------------------------|---|
| 1, 5 to 7, 9, 10, 12 to 14, 18, 19, 24 | NIC | Not Internally Connected. However, all data was measured with these pins connected to RF/dc ground externally. |
| 2, 4, 15, 17 | GND | Ground. These pins must be connected to RF/dc ground. |
| 3 | RFIN | RF Input. This pin is ac-coupled and matched to 50 Ω. |
| 8 | V _{GG1} | Gate Bias Pin for the First and Second Stages. External bypass capacitors of 100 pF, 10 nF, and 4.7 μF are required for this pin. |
| 11 | V _{GG2} | Gate Bias Pin for the Third and Fourth Stages. External bypass capacitors of 100 pF, 10 nF, and 4.7 μF are required for this pin. |
| 16 | RFOUT | RF Output. This pin is ac-coupled and matched to 50 Ω. |
| 20 to 23 | V _{DD4} to V _{DD1} | Drain Bias Voltage Pins. External bypass capacitors of 100 pF, 10 nF, and 4.7 μF are required for these pins. |
| | EPAD | Exposed Pad. The exposed pad must be connected to RF/dc ground. |

INTERFACE SCHEMATICS

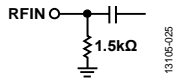


Figure 3. RFIN Interface Schematic

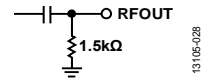


Figure 6. RFOUT Interface Schematic



Figure 4. GND Interface Schematic

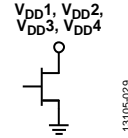


Figure 7. VDD1 to VDD4 Interface Schematic

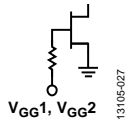


Figure 5. VGG1/VGG2 Interface Schematic

TYPICAL PERFORMANCE CHARACTERISTICS

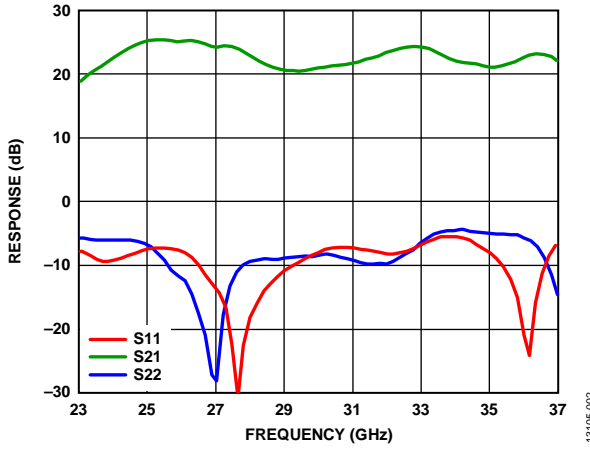


Figure 8. Response (Broadband Gain and Return Loss) vs. Frequency

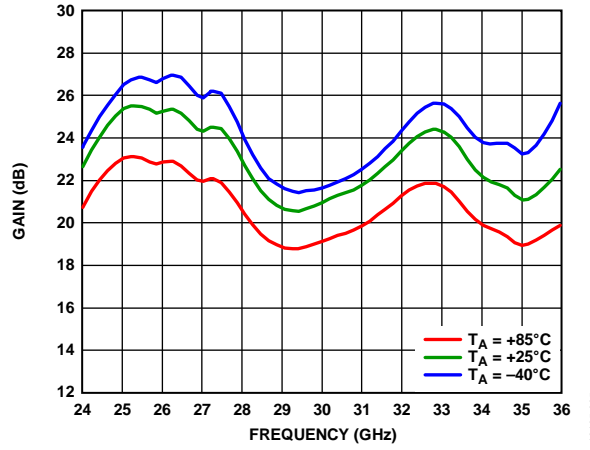


Figure 11. Gain vs. Frequency at Various Temperatures

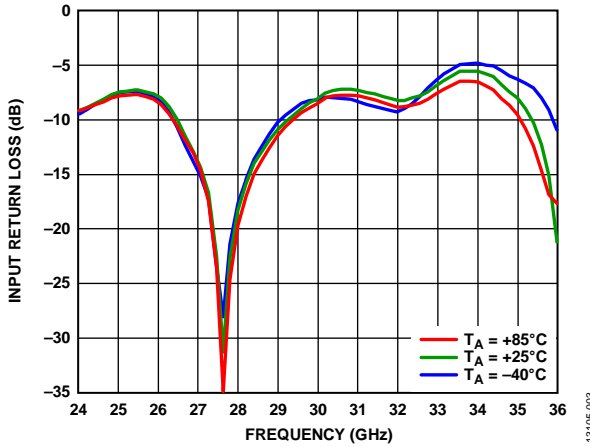


Figure 9. Input Return Loss vs. Frequency at Various Temperatures

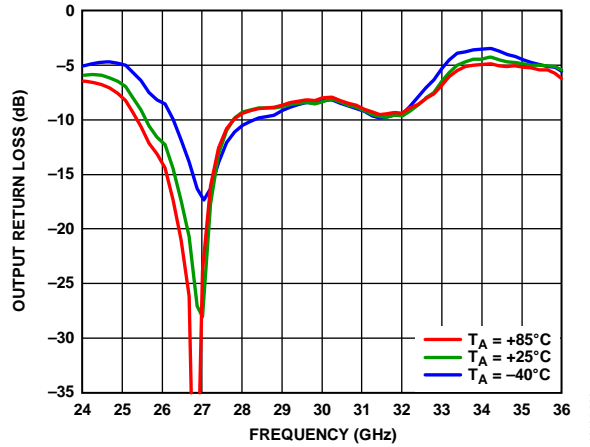


Figure 12. Output Return Loss vs. Frequency at Various Temperatures

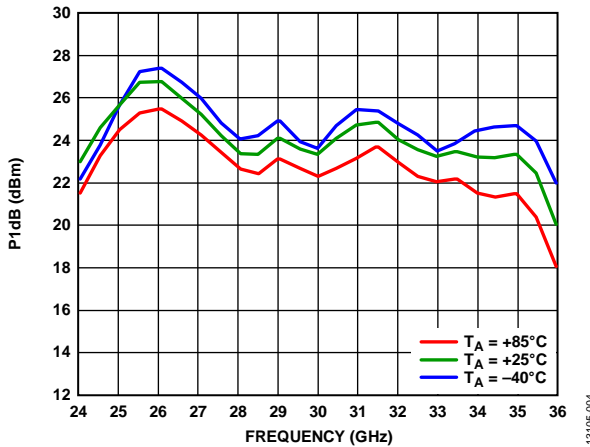


Figure 10. P1dB vs. Frequency at Various Temperatures

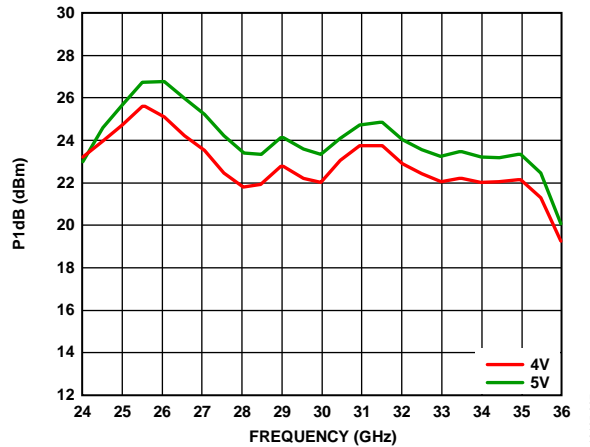


Figure 13. P1dB vs. Frequency at Various Supply Voltages

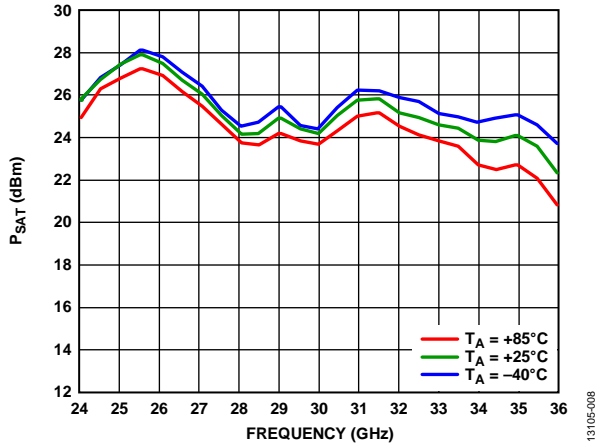


Figure 14. P_{SAT} vs. Frequency at Various Temperatures

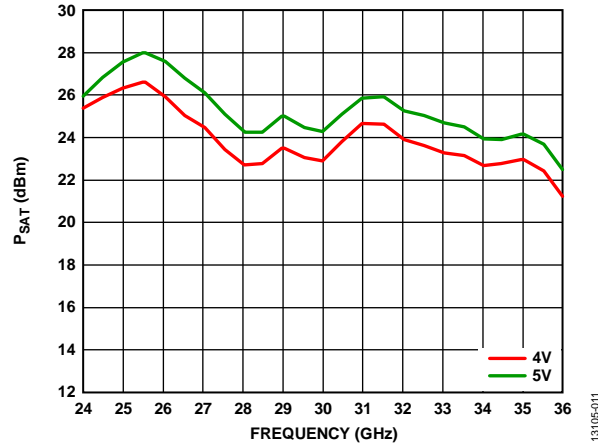


Figure 17. P_{SAT} vs. Frequency at Various Supply Voltages

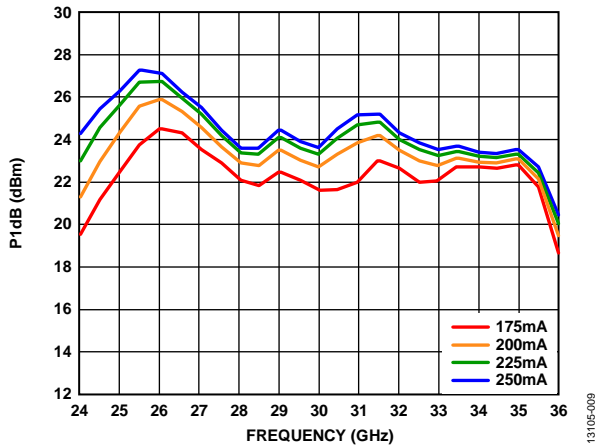


Figure 15. P_{1dB} vs. Frequency at Various Supply Currents

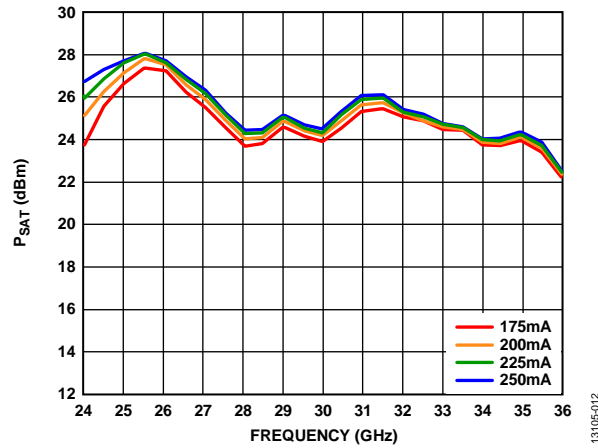


Figure 18. P_{SAT} vs. Frequency at Various Supply Currents

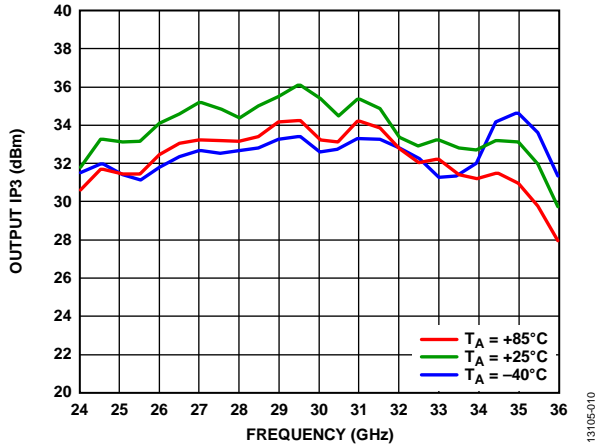


Figure 16. Output IP_3 vs. Frequency at Various Temperatures, $P_{OUT}/Tone = 10\text{ dBm}$

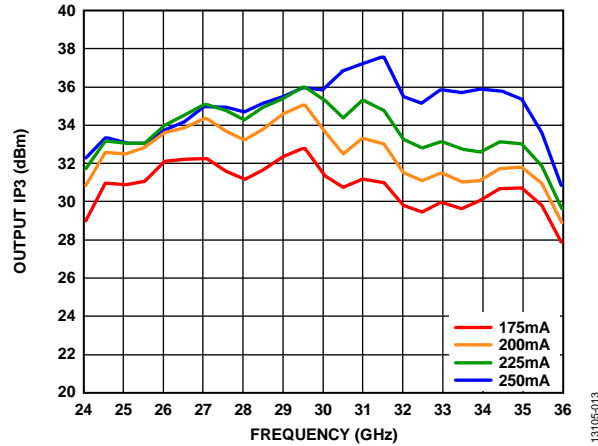


Figure 19. Output IP_3 vs. Frequency at Various Supply Currents, $P_{OUT}/Tone = 10\text{ dBm}$

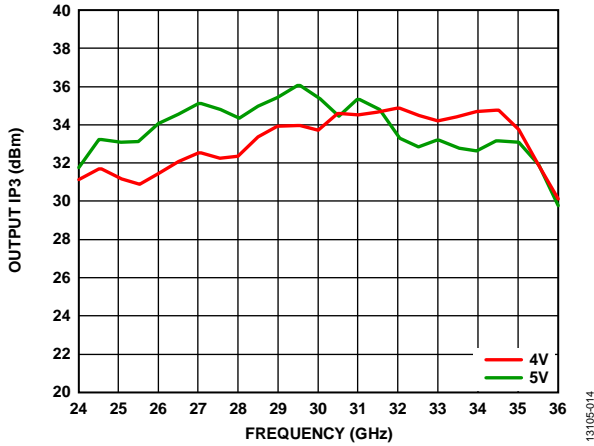


Figure 20. Output IP3 vs. Frequency for Various Supply Voltages, $P_{OUT/Tone} = 10$ dBm

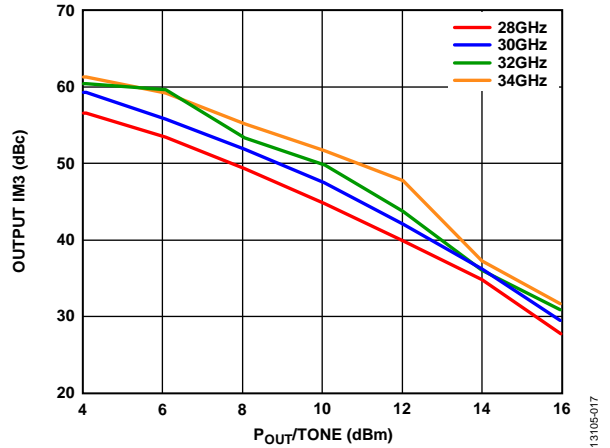


Figure 23. Output Third-Order Intermodulation (IM3) vs. $P_{OUT/Tone}$ at $V_{DD} = 4$ V

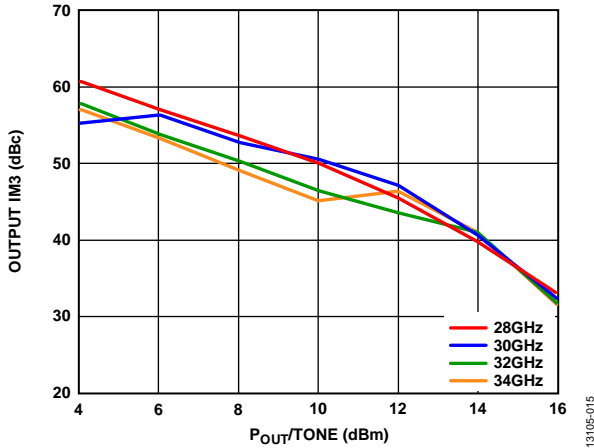


Figure 21. Output Third-Order Intermodulation (IM3) vs. $P_{OUT/Tone}$ at $V_{DD} = 5$ V

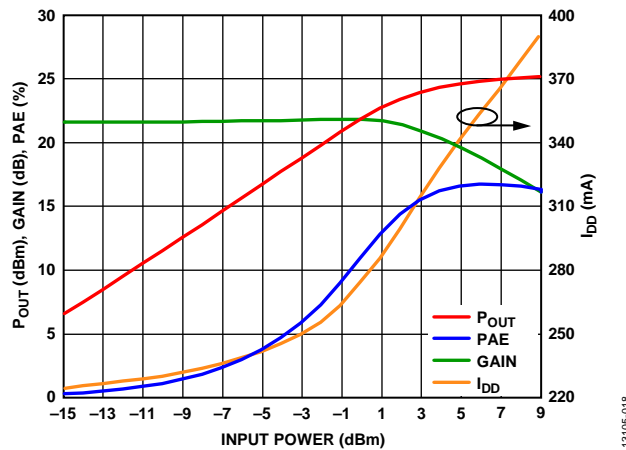


Figure 24. Power Compression at 30.5 GHz (PAE Is Power Added Efficiency)

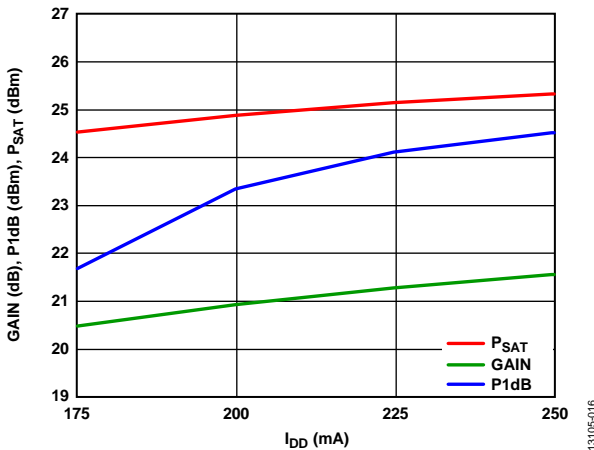


Figure 22. Gain, P1dB, and P_{SAT} vs. Supply Current (I_{DD}) at 30.5 GHz

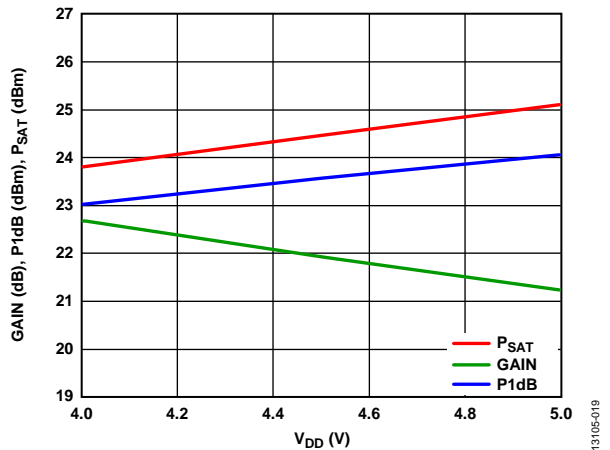


Figure 25. Gain, P1dB, and P_{SAT} vs. Supply Voltage (V_{DD}) at 30.5 GHz

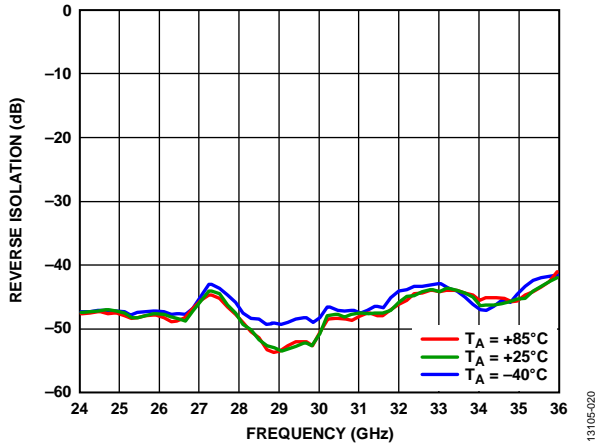


Figure 26. Reverse Isolation vs. Frequency at Various Temperatures

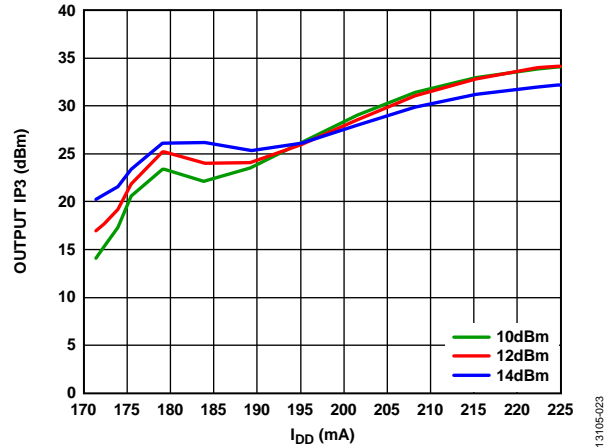


Figure 29. Output IP3 vs. I_{DD} over P_{OUT} /Tone at 30 GHz, $V_{DD} = 5 V$, $I_{DD} = 225 mA$, $I_{DD2} = \text{Fixed}$, and I_{DD1} Varied from 0 mA to 50 mA

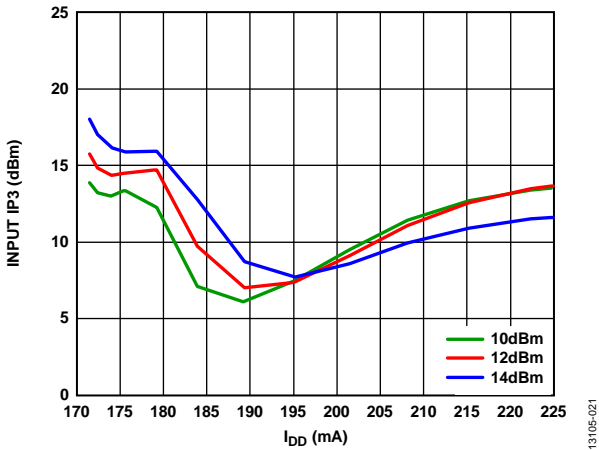


Figure 27. Input IP3 vs. I_{DD} over P_{OUT} /Tone at 30 GHz, $V_{DD} = 5 V$, $I_{DD} = 225 mA$, $I_{DD2} = \text{Fixed}$, and I_{DD1} Varied from 0 mA to 50 mA

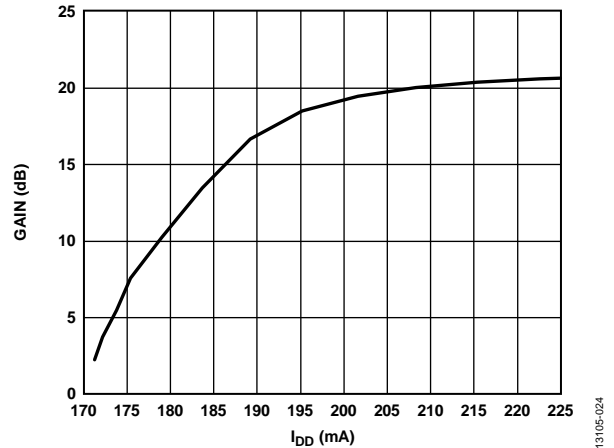


Figure 30. Gain vs. I_{DD} over P_{OUT} /Tone = 14 dBm at 30 GHz, $V_{DD} = 5 V$, $I_{DD} = 225 mA$, $I_{DD2} = \text{Fixed}$, and I_{DD1} Varied from 0 mA to 50 mA

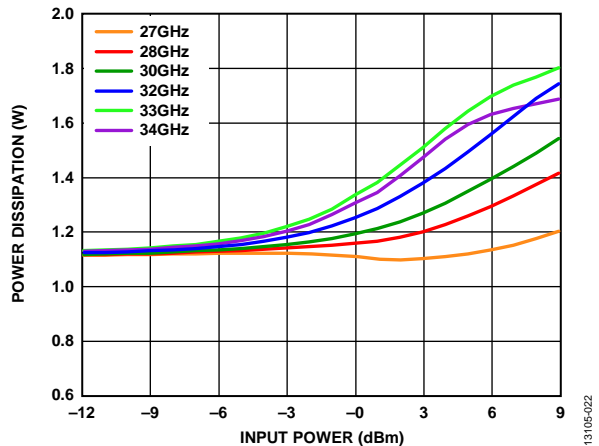


Figure 28. Power Dissipation (P_{DISS}) at 85°C vs. Input Power for Various Frequencies

13105-020

13105-023

13105-021

13105-024

13105-022

APPLICATIONS INFORMATION

The **HMC1131** is a GaAs, pHEMT, MMIC, medium power amplifier consisting of four gain stages in series. V_{GG1} is the gate bias pin for the first and second stages, while V_{GG2} is the gate bias pin for the third and fourth stages. A simplified block diagram is shown in Figure 31.

All measurements for this device were taken using the evaluation printed circuit board (PCB) in its default configuration. Unless otherwise noted, the V_{GG1} , V_{GG2} , and V_{DD1} to V_{DD4} pins were tied together during measurement, respectively.

The following is the recommended bias sequence during power-up:

1. Connect to ground.
2. Set V_{GG1} and V_{GG2} to -2 V.
3. Set V_{DD1} through V_{DD4} to 5 V.
4. Increase V_{GG1} and V_{GG2} to achieve a quiescent $I_{DD} = 225$ mA.
5. Apply the RF signal.

The following is the recommended bias sequence during power-down:

1. Turn the RF signal off.
2. Decrease V_{GG1} and V_{GG2} to -2 V to achieve a quiescent $I_{DD} = 0$ mA (approximately).
3. Decrease V_{DD1} through V_{DD4} to 0 V.
4. Increase V_{GG1} and V_{GG2} to 0 V.

The $V_{DDX} = 5$ V and $I_{DD} = 225$ mA bias conditions are the operating points recommended to optimize the overall performance. Unless otherwise noted, the data shown was taken using the recommended bias conditions. Operation of the **HMC1131** at different bias conditions may result in performance that differs from that shown in Figure 27 and Figure 30. Biasing the **HMC1131** for higher drain current typically results in higher P1dB, OIP3, and gain but at the expense of increased power consumption.

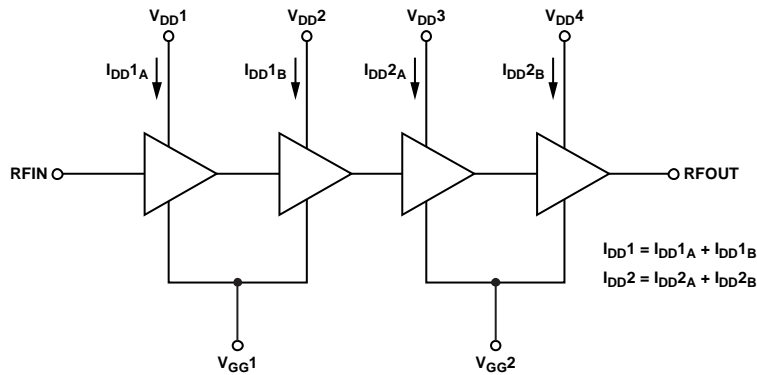


Figure 31. Simplified Block Diagram

EVALUATION PCB

Generate the evaluation PCB used in this application with proper RF circuit design techniques. Signal lines at the RF port must have 50 Ω impedance, and the package ground leads and

exposed paddle must be connected directly to the ground plane similar to what is shown in Figure 32. Use a sufficient number of via holes to connect the top and bottom ground planes.

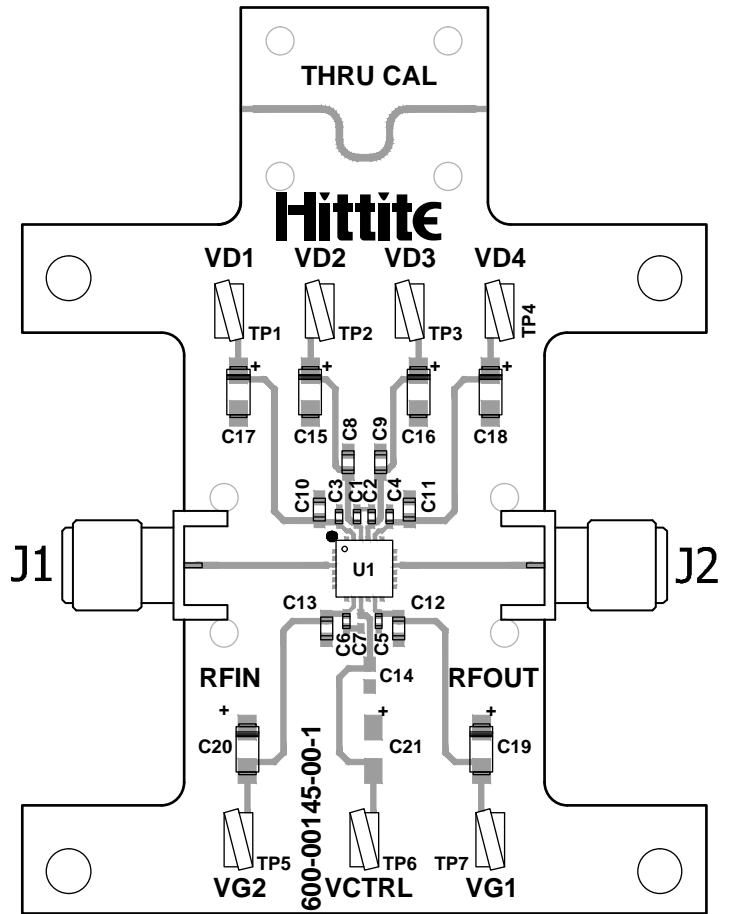


Figure 32. 600-00145-00-1 Evaluation PCB

Bill of Materials

Table 5. Evaluation Board (EV1HMC1131LC4) Bill of Materials

| Item | Description | Manufacturer ¹ |
|------------|---|--------------------------------------|
| J1, J2 | PCB mount, K connector | |
| TP1 to TP7 | DC pin | |
| C1 to C6 | 100 pF capacitors, 0402 package | |
| C8 to C13 | 10000 pF capacitors, 0402 package | |
| C15 to C20 | 2.2 μF capacitors, 0402 package | |
| U1 | HMC1131LC4 | Analog Devices, Inc. |
| PCB | 600-00145-00-1 evaluation board, Rogers 4350 or Arlon 25FR circuit board material | 600-00145-00-1, Analog Devices, Inc. |

¹ Blank cells in the manufacturer column left blank intentionally for they are user selectable.

TYPICAL APPLICATION CIRCUIT

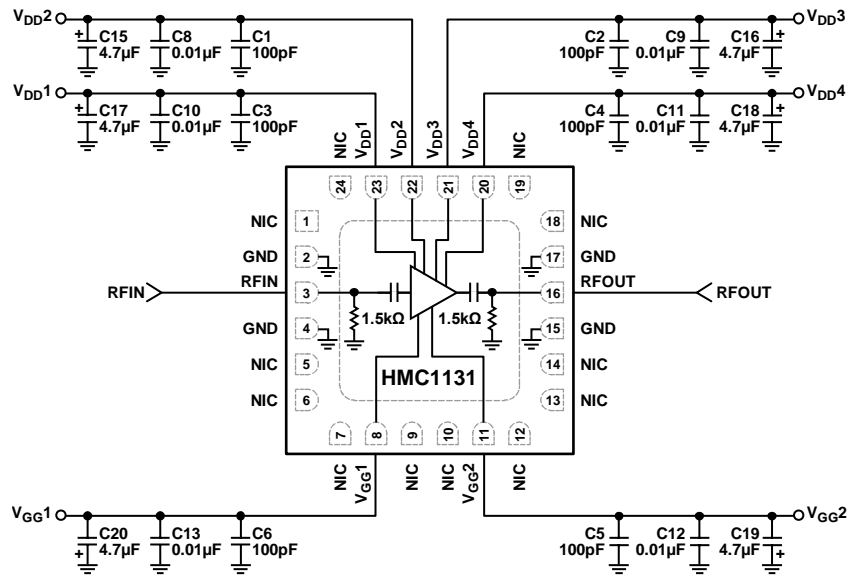


Figure 33. Typical Application Circuit

131105-6030

OUTLINE DIMENSIONS

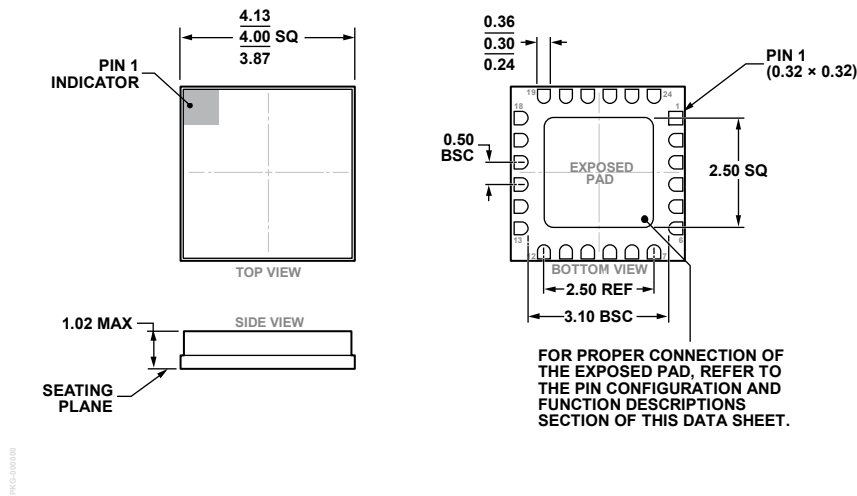


Figure 34. 24-Terminal Ceramic Leadless Chip Carrier [LCC] (HE-24-1)
Dimensions shown in millimeters

ORDERING GUIDE

| Model ¹ | Temperature Range | MSL Rating ² | Lead Finish | Package Description | Package Option | Branding ³ |
|--------------------|-------------------|-------------------------|------------------|---------------------|----------------|-----------------------|
| HMC1131LC4 | -40°C to +85°C | MSL3 | Gold over Nickel | 24-Terminal LCC | HE-24-1 | H1131 XXXX |
| HMC1131LC4TR | -40°C to +85°C | MSL3 | Gold over Nickel | 24-Terminal LCC | HE-24-1 | H1131 XXXX |
| EV1HMC1131LC4 | | | | Evaluation Board | | |

¹ The HMC1131LC4 and the HMC1131LC4TR are RoHS Compliant.

² See the Absolute Maximum Ratings section.

³ XXXX is the 4-digit lot number.